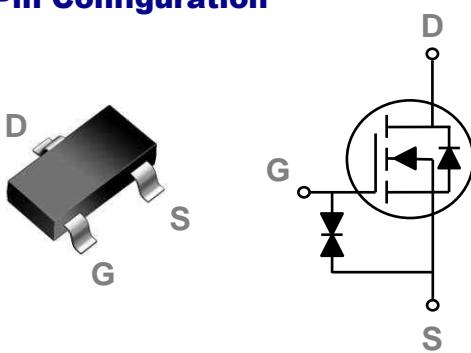


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT323 Pin Configuration



BVDSS	RDS(ON)	ID
60V	3Ω	300mA

### Features

- 60V, 300mA, RDS(ON) = 3Ω@VGS = 10V
- Improved dv/dt capability
- Fast switching
- ESD protected up to 2KV
- Green Device Available

### Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GС</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	300	mA
	Drain Current – Continuous (T <sub>A</sub> =70°C)	240	mA
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	1.2	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	313	mW
	Power Dissipation – Derate above 25°C	2.5	mW/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	450	°C/W



60V N-Channel MOSFETs

PDEU69A8Z

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.05	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =85°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±20	uA

**On Characteristics**

R <sub>Ds(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =0.3A	---	1.1	3	Ω
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.2A	---	1.3	4	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	2.1	3	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	3	---	

**Dynamic and switching Characteristics**

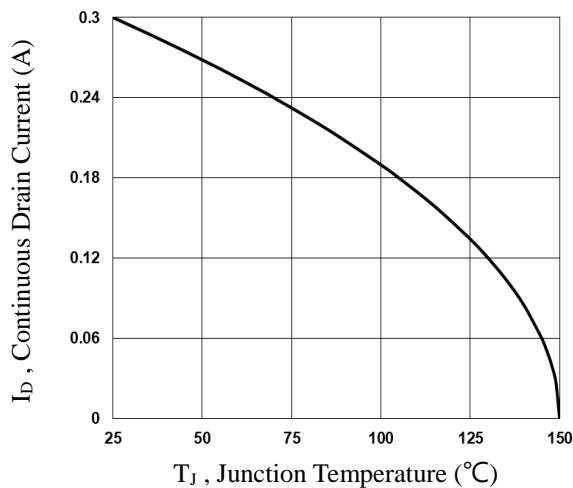
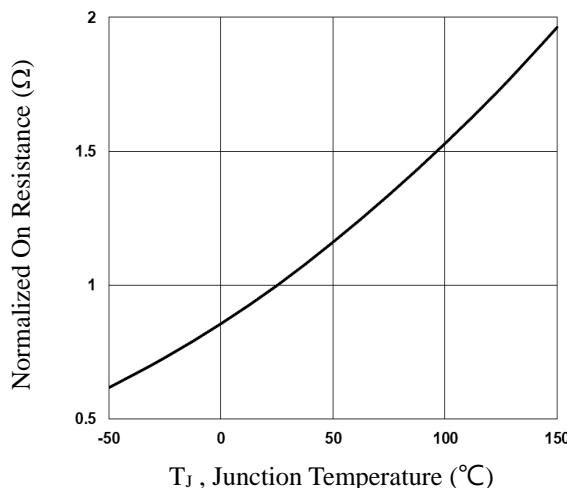
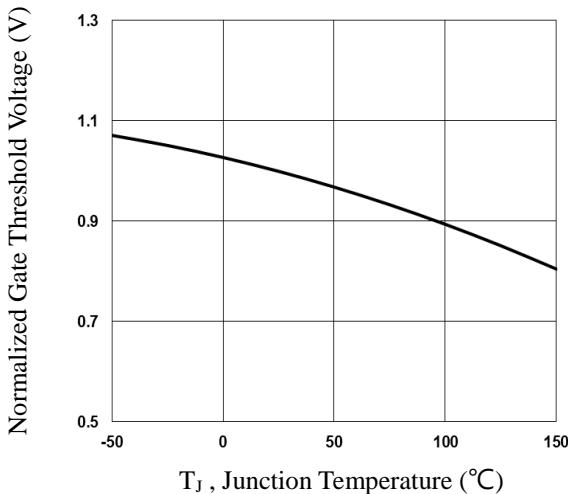
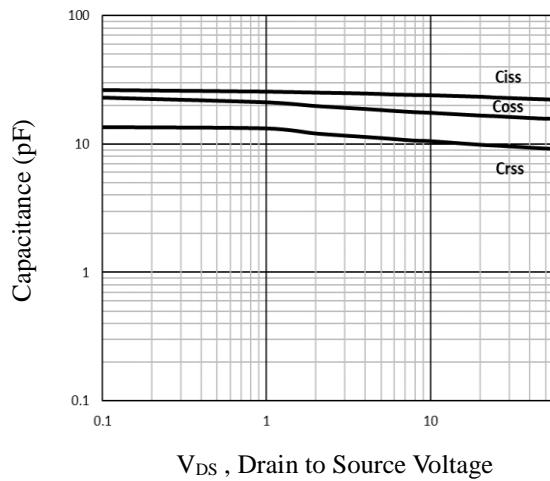
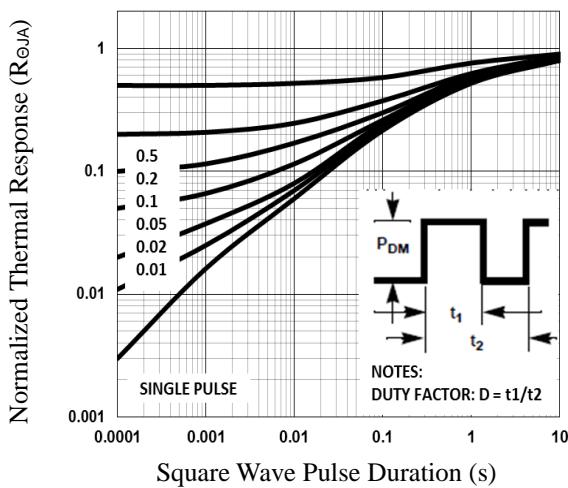
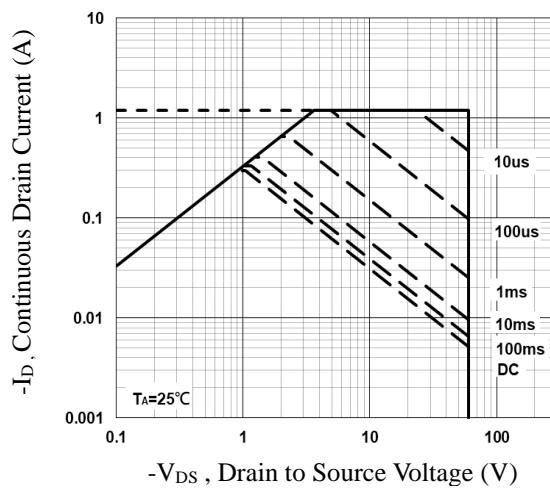
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , F=1MHz	---	23	46	pF
C <sub>oss</sub>	Output Capacitance		---	16	32	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	10	20	

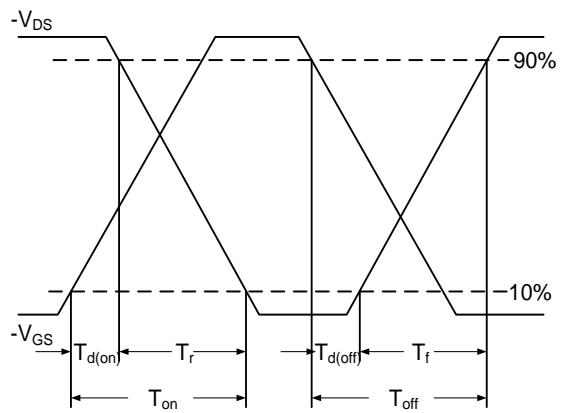
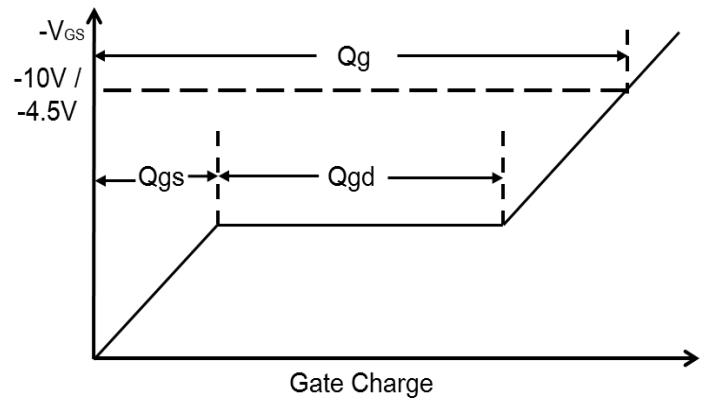
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	300	mA
I <sub>SM</sub>	Pulsed Source Current		---	---	600	mA
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =0.2A , T <sub>J</sub> =25°C	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_J$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Capacitance Characteristics**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

## SOT323 PACKAGE INFORMATION

